

# CHIPQUIK® SMDAU80SN20-3inch-0.762mm

Datasheet revision 1.3

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## Solder Wire (Au80/Sn20) Gold/Tin Eutectic 0.030"/0.762mm diameter - 3 inches

### Product Highlights

Gold/Tin 80/20 Eutectic Solder Alloy

Lead-Free

RoHS 3 compliant

REACH compliant

Gold/Tin (80 percent Gold, 20 percent Tin) Solid Core Solder Wire. Eutectic, melts at 280°C (536°F). Au80/Sn20 alloy offers good wetting, high strength, and low creep. It has excellent corrosion resistance and a high thermal conductivity. Au80/Sn20 can be brazed without flux and is suitable for use in vacuum environments. This alloy is used in many applications, including die attachment of semiconductor packages and metal lids.



### Common Applications

High Reliability

Die Attachment

Lid Sealing

Brazing

### Specifications

Alloy:	Au80/Sn20
Diameter:	0.030" (0.762mm)
Length:	3" (76.2mm)
Net Weight:	0.5 grams
Melting Point:	280°C (526°F)
Flux Core:	Solid core wire, no flux
Density:	14.51 g/cm <sup>3</sup>
Tensile Strength:	40,000 psi
Shear Strength:	40,000 psi
Young's Modulus:	8.57 x10 <sup>6</sup> psi
CTE (Coefficient of Thermal Expansion):	16 ppm/C (at 20C)
Thermal Conductivity:	57 W/mK
Shelf Life:	>60 months

### Recommended Accessory Flux

Recommended to use with Chip Quik® SMD291NL flux.

### Storage and Handling

Store in a non-corrosive, dry environment.